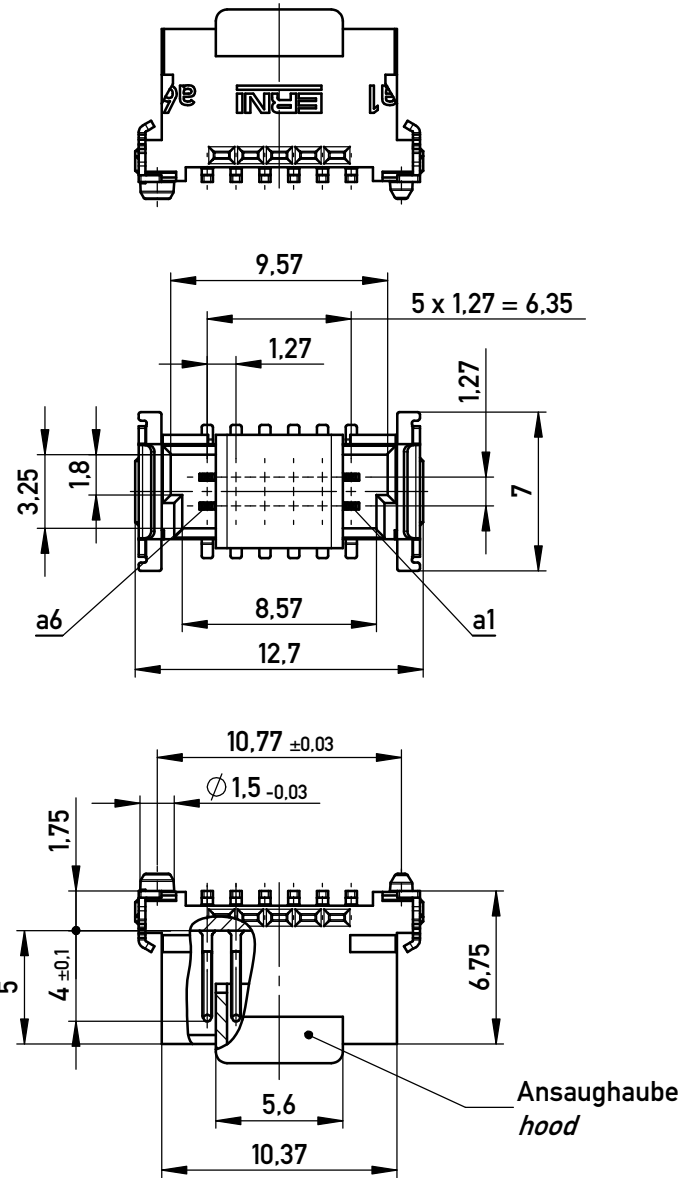


Verpackt im Gurt nach DIN IEC 60286-3  
 Tape on Reel Packaging according to DIN IEC 60286-3  
 Verpackungseinheit: 280 Stück  
 Packaging unit: 280 pcs

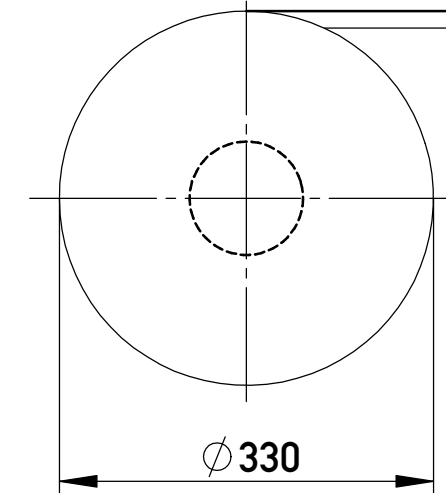


Anforderungsstufe 1  
 Performance Level 1

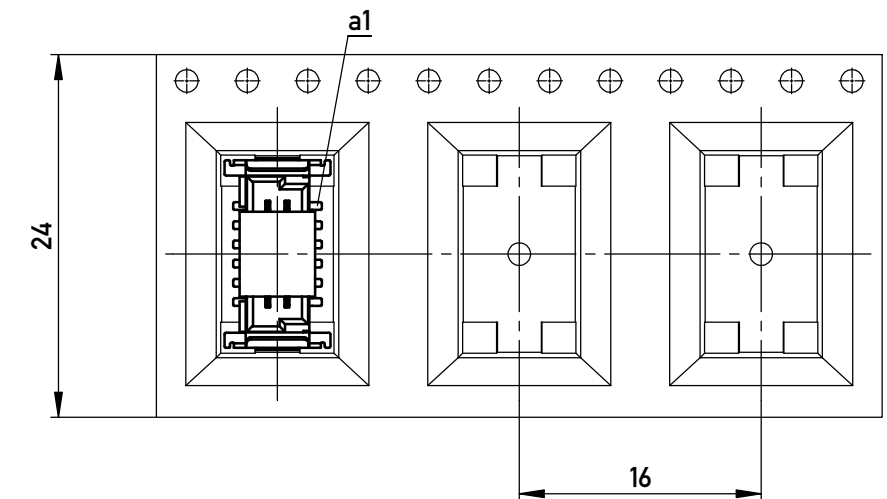
Kontaktbereich vergoldet  
 Mating Area gold plating

Anschlussbereich verzinkt 4-6 µm  
 Terminal Area 4-6 µm tin plating

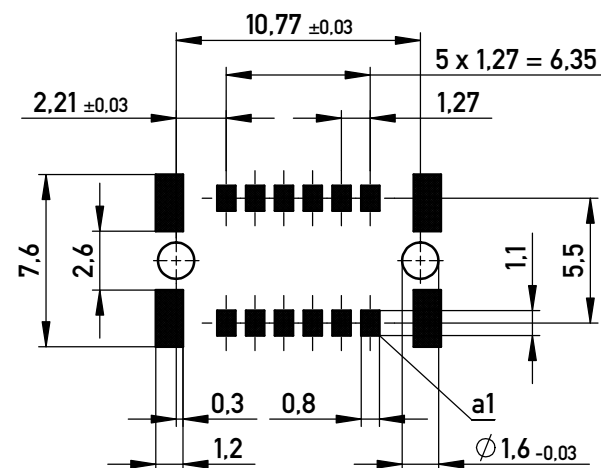
Koplanarität der Anschlüsse ≤ 0,1 mm  
 Coplanarity Area of Termination ≤ 0,1 mm



Abspulrichtung - Reel off Direction



Leiterplatten-Layout Vorschlag für SMT  
 PCB-Layout Proposal for SMT



BA 8-13 - 8mm Bauhöhe

type 8-13 - Low Profile

|  |            |   |                          |   |     |
|--|------------|---|--------------------------|---|-----|
| Information:   |            | Tolerances  | <br>All Dimensions in mm | Scale   | 3:1 |
| All rights reserved.<br>Only for Information.<br>To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using. |            | Subject to modification without prior notice.<br>Drawing will not be updated. |                          | Designation<br><b>Messerl. SMC-Q 12-SMD-BA8-13</b><br><i>Male SMC-Q 12-SMD-type8-13</i> |     |
| <br>www.ERNI.com   |            | <b>100203210050</b>   |                          | K<br>A3   |     |
| d  | 06.06.2014 | Class   |                          | SMCQ  |     |
| Index  | Date       |   |                          |   |     |

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